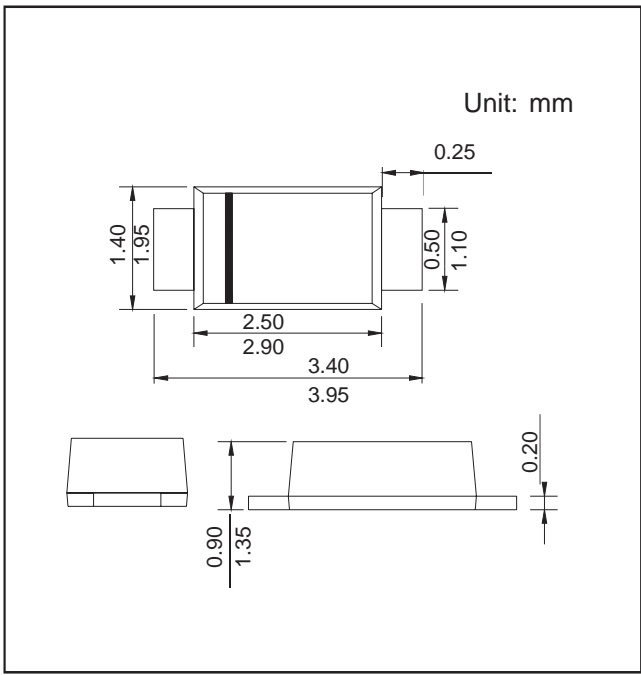


62' )/

For surface mounted application  
 Glass passivated device  
 Low forward voltage drop  
 High current capability  
 Easy pick and place

Plastic material used carriers Underwriters  
 Laboratory Classification 94V-O  
 High temperature soldering guaranteed:  
 250 C/10 seconds

Case : JEDEC SOD-123FL molded plastic bodyover  
 passivated chip  
 Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026  
 Polarity: Color band denotes cathode end Mounting  
 Position: Any



@ 25°C Ambient Temperature (unless otherwise noted)

| Parameter                                                                                                            | Symbols         | A1          | A2  | A3  | A4  | A5  | A6  | A7   | Units        |
|----------------------------------------------------------------------------------------------------------------------|-----------------|-------------|-----|-----|-----|-----|-----|------|--------------|
| Maximum Recurrent Peak Reverse Voltage                                                                               | $V_{RRM}$       | 50          | 100 | 200 | 400 | 600 | 800 | 1000 | Volts        |
| Maximum RMS Voltage                                                                                                  | $V_{RMS}$       | 35          | 70  | 140 | 280 | 420 | 560 | 700  | Volts        |
| Maximum DC Blocking Voltage                                                                                          | $V_{DC}$        | 50          | 100 | 200 | 400 | 600 | 800 | 1000 | Volts        |
| Maximum average Forward Rectified Current<br>0.375" (9.5mm) length at $T_J = 75^\circ C$                             | $I_{(AV)}$      | 1.0         |     |     |     |     |     |      | Amp          |
| Peak Forward Surge Current (8.3ms half sine-wave superimposed on rated load)<br>(JEDEC method) at $T_J = 75^\circ C$ | $I_{FSM}$       | 30.0        |     |     |     |     |     |      | Amps         |
| Maximum Instantaneous Forward Voltage at 1A0                                                                         | $V_F$           | 1.0         |     |     |     |     |     |      | Volts        |
| Maximum Reverse current at rated DC Voltage<br>$T_J = 25^\circ C$<br>$T = 100^\circ C$                               | $I_R$           | 5.0         |     |     |     |     |     |      | $\mu A$      |
|                                                                                                                      |                 | 50.0        |     |     |     |     |     |      |              |
| Typical Thermal resistance (Note 2)                                                                                  | $R_{\theta JA}$ | 65.0        |     |     |     |     |     |      | $^\circ C/W$ |
| Typical Junction Capacitance (Note 1)                                                                                | $C_j$           | 10.0        |     |     |     |     |     |      | pF           |
| Maximum DC Blocking Voltage                                                                                          | $T_A$           | +150        |     |     |     |     |     |      | $^\circ C$   |
| Operating and Storage temperature range                                                                              | $T_J$           | -55 to +150 |     |     |     |     |     |      | $^\circ C$   |
|                                                                                                                      | $T_{STG}$       |             |     |     |     |     |     |      |              |

Note 1: Measured at 1MHz and applied reverse voltage of 4.0V DC.  
 2. Thermal resistance from junction to ambient at 0.375" (9.5mm) height, P.C. mounted

